

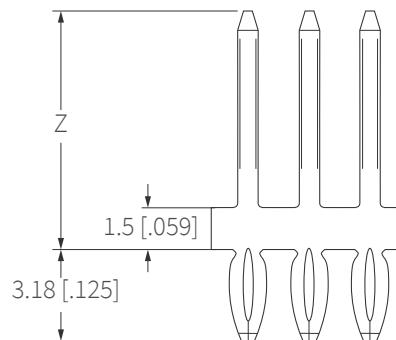
## 1.5 BLADE PRESS-FIT TERMINAL SPECIFICATIONS

TYPE	PART NUMBER	MATERIAL	SIZE	Z LENGTH		PCB HOLE SIZE	CARRIER TYPE	CURRENT CAPACITY STANDARD	CURRENT CAPACITY HI-TEMP
				MM	INCH				
1.5 Blade	7-V5068-001ST	Hi Temp	1.5 x .64	16.00	0.630	A	Side Carrier	7A	15A
	7-V5068-011TT	Hi Temp	1.5 x .64	14.70	0.579	A	Side Carrier	8A	16A
	7-V5077-001TA	Hi Temp	1.5 x .64	11.75	0.463	A	Side Carrier	10A	20A

### NOTE:

- Current Carrying Capacity (Current Rating) for  $\Delta T = 30^\circ\text{C}$  Heat Rise
- Current Carrying Capacity (Current Rating) for C42520 is defined per: SAE/USCAR-2 - Revision 5 - Section 5.3.3, EIA Publication 364 - Procedure 70 thru the testing
- Current Carrying Capacities (Current Rating) for C19010 are defined using C42520 data and theoretical formula
- All current ratings must be verified during validation testing of the final assembly

### Side Carrier



## PRESS-FIT PCB HOLE SIZE REQUIREMENTS

HOLE SIZE	COMPONENT THICKNESS	FINISHED HOLE DIAMETER	DESCRIPTION	PC BOARD DIMENSIONS
A	0.64 mm	1.05 mm	Drilled Hole	1.15 $\pm$ 0.025 mm
			Copper Plating	
			Plating Thickness	25 $\mu\text{m}$ min
			Hole Diameter	1.05 $\pm$ 0.05 mm
			Finished Hole	
			Tin Plating Thickness	2 $\mu\text{m}$ -8 $\mu\text{m}$
			Plated Hole Diameter	1.05 $\pm$ 0.05 mm
			Precious metal Plated (Note 2)	1.05 $\pm$ 0.05 mm

### NOTE:

1. Tin thickness applies to tin-lead and lead free plating.

2. Precious metal plating types:

#### Immersion Au:

0.08  $\mu\text{m}$ -0.13  $\mu\text{m}$  [3  $\mu\text{in}$ -5  $\mu\text{in}$ ] Gold over 3.8  $\mu\text{m}$ -7.6  $\mu\text{m}$  [150  $\mu\text{in}$ -300  $\mu\text{in}$ ] Nickel

#### Immersion Ag:

0.2  $\mu\text{m}$ -0.5  $\mu\text{m}$  [8  $\mu\text{in}$  -20  $\mu\text{in}$ ]